



Highlights

- Innovative polishing pad for Pureon's Rapid Thinning process
- Best choice for SiC polishing
- Surface finishes down to 3 nm Ra
- Highly competitive compared to grinding processes
- Provides excellent workpiece geometry and flatness, without edge round-off
- Dressable system, suitable for single-side and double-side machines
- Best results if used with PURE-DS-RT suspensions from Pureon

Composite polishing pad

IRINO-PROSiC

Introducing the IRINO-PROSiC composite polishing pad, a cutting-edge addition to our IRINO family of composite polishing pads. Specifically engineered for the polishing of Silicon Carbide (SiC), IRINO-PROSiC is designed to deliver superior results in SiC DMP (Direct Mechanical Planarization) processes.

When paired with the suspension PURE-DS-RT, IRINO-PROSiC excels in the Rapid Thinning process, offering a highly competitive alternative to traditional SiC DMP grinding methods. This innovative combination not only achieves exceptional surface quality but also ensures impressive stock removal rates, making it ideal for applications requiring a smooth transition directly to CMP (Chemical Mechanical Planarization).

With its self-adhesive backing, IRINO-PROSiC can be effortlessly applied to any existing metal carrier plate, enhancing ease of use and efficiency in SiC polishing applications. Whether you seek high surface quality or superior material removal, IRINO-PROSiC is the optimal choice for advanced SiC processing.



IRINO-PROSiC composite polishing pad.



IRINO-PROSiC composite polishing pads are recommended to be used with PURE-DS-RT diamond suspensions.



Pureon offers a wide range of customized solutions. Get in touch with us.

Product specifications

Abrasive layer thickness 1 mm
Bond type Resin
Carrier material Polycarbonate
Typical application SiC wafers

Order information

Order code IRINO-PROSiC OD475-ID200mm-PU1-PSA-D1
1 2 3 4 5

- 1 Outer diameter 200 – 1'200 mm one-piece
For bigger diameters multi-piece
Custom sizes are available upon request
- 2 Inner diameter Optional (freely selectable)
- 3 Packing unit 1 piece / box
- 4 Backing / mounting PSA (self-adhesive)
- 5 Drawing index Optional

Application recommendations

Dressing Prior to the first use, the IRINO-PROSiC pad has to be dressed and planarized with our dressing tool MicroDress.

Diamond suspension feed PURE-DS-RT suspension is recommended and a water-soluble diamond suspension that ensures high and consistent material removal. No dry running. Organic solvent and oil-based suspensions may harm the pad and are therefore not recommended.

Polishing parameters

Polishing pressure Recommended: 0,2 kg/cm²
Circumferential speed Recommended: 2 m/s, max. 3 m/s

Contact

sales@pureon.com
www.pureon.com

